

MMBT2369LT1G, MMBT2369ALT1G

Switching Transistors

NPN Silicon

Features

- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	15	Vdc
Collector - Emitter Voltage	V_{CES}	40	Vdc
Collector - Base Voltage	V_{CBO}	40	Vdc
Emitter - Base Voltage	V_{EBO}	4.5	Vdc
Collector Current - Continuous	I_C	200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

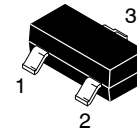
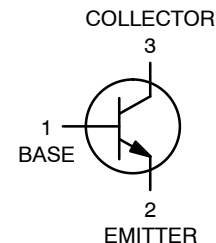
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



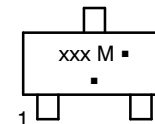
ON Semiconductor®

<http://onsemi.com>



SOT-23
CASE 318
STYLE 6

MARKING DIAGRAM



xxx = M1J or 1JA
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping
MMBT2369LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBT2369ALT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 3) (I _C = 10 mA, I _B = 0)	V _{(BR)CEO}	15	–	–	Vdc
Collector – Emitter Breakdown Voltage (I _C = 10 μA, V _{BE} = 0)	V _{(BR)CES}	40	–	–	Vdc
Collector – Base Breakdown Voltage (I _C = 10 μA, I _E = 0)	V _{(BR)CBO}	40	–	–	Vdc
Emitter – Base Breakdown Voltage (I _E = 10 μA, I _C = 0)	V _{(BR)EBO}	4.5	–	–	Vdc
Collector Cutoff Current (V _{CB} = 20 Vdc, I _E = 0) (V _{CB} = 20 Vdc, I _E = 0, T _A = 150°C)	I _{CBO}	–	–	0.4 30	μA
Collector Cutoff Current (V _{CE} = 20 Vdc, V _{BE} = 0)	I _{CES}	–	–	0.4	μA
ON CHARACTERISTICS					
DC Current Gain (Note 3) (I _C = 10 mA, V _{CE} = 1.0 Vdc) (I _C = 10 mA, V _{CE} = 1.0 Vdc) (I _C = 10 mA, V _{CE} = 0.35 Vdc) (I _C = 10 mA, V _{CE} = 0.35 Vdc, T _A = –55°C) (I _C = 30 mA, V _{CE} = 0.4 Vdc) (I _C = 100 mA, V _{CE} = 2.0 Vdc) (I _C = 100 mA, V _{CE} = 1.0 Vdc)	h _{FE}	40 – 40 20 30 20 20	– – – – – – –	120 120 – – – – –	–
Collector – Emitter Saturation Voltage (Note 3) (I _C = 10 mA, I _B = 1.0 mA) (I _C = 10 mA, I _B = 1.0 mA) (I _C = 10 mA, I _B = 1.0 mA, T _A = +125°C) (I _C = 30 mA, I _B = 3.0 mA) (I _C = 100 mA, I _B = 10 mA)	V _{CE(sat)}	– – – – –	– – – – –	0.25 0.20 0.30 0.25 0.50	Vdc
Base – Emitter Saturation Voltage (Note 3) (I _C = 10 mA, I _B = 1.0 mA) (I _C = 10 mA, I _B = 1.0 mA, T _A = –55°C) (I _C = 30 mA, I _B = 3.0 mA) (I _C = 100 mA, I _B = 10 mA)	V _{BE(sat)}	0.7 – – –	– – – –	0.85 1.02 1.15 1.60	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Output Capacitance (V _{CB} = 5.0 Vdc, I _E = 0, f = 1.0 MHz)	C _{obo}	–	–	4.0	pF
Small Signal Current Gain (I _C = 10 mA, V _{CE} = 10 Vdc, f = 100 MHz)	h _{fe}	5.0	–	–	–
SWITCHING CHARACTERISTICS					
Storage Time (I _{B1} = I _{B2} = I _C = 10 mA)	t _s	–	5.0	13	ns
Turn-On Time (V _{CC} = 3.0 Vdc, I _C = 10 mA, I _{B1} = 3.0 mA)	t _{on}	–	8.0	12	ns
Turn-Off Time (V _{CC} = 3.0 Vdc, I _C = 10 mA, I _{B1} = 3.0 mA, I _{B2} = 1.5 mA)	t _{off}	–	10	18	ns

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

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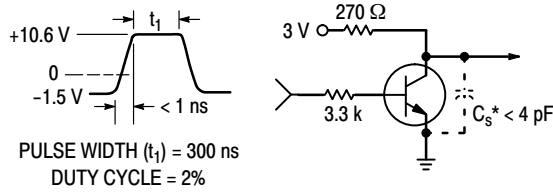


Figure 1. t_{on} Circuit – 10 mA

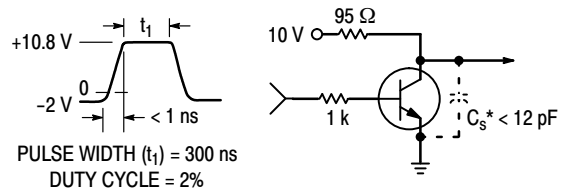


Figure 2. t_{on} Circuit – 100 mA

*Total shunt capacitance of test jig and connectors.

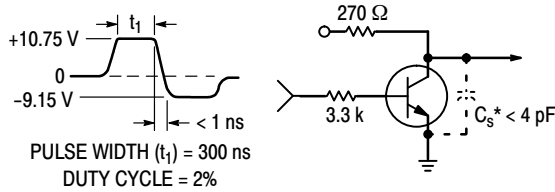


Figure 3. t_{off} Circuit – 10 mA

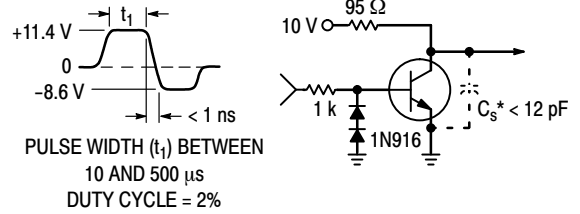
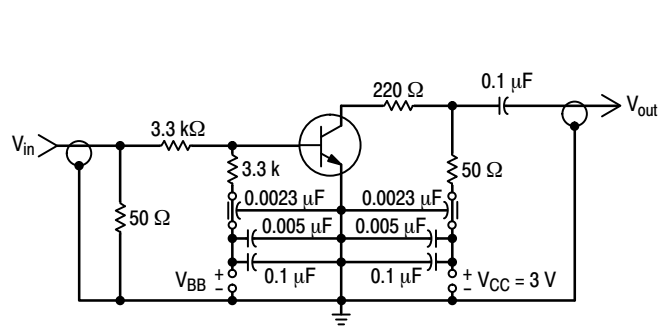
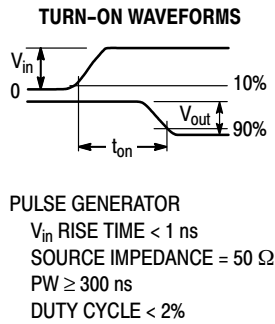


Figure 4. t_{off} Circuit – 100 mA

*Total shunt capacitance of test jig and connectors.



TO OSCILLOSCOPE
INPUT IMPEDANCE = 50 Ω
RISE TIME = 1 ns

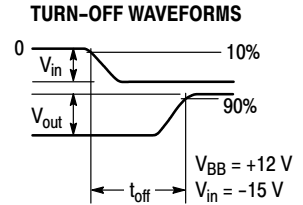


Figure 5. Turn-On and Turn-Off Time Test Circuit

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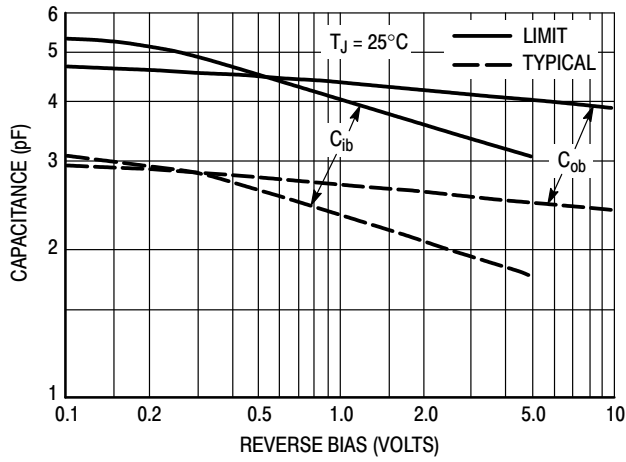


Figure 6. Junction Capacitance Variations

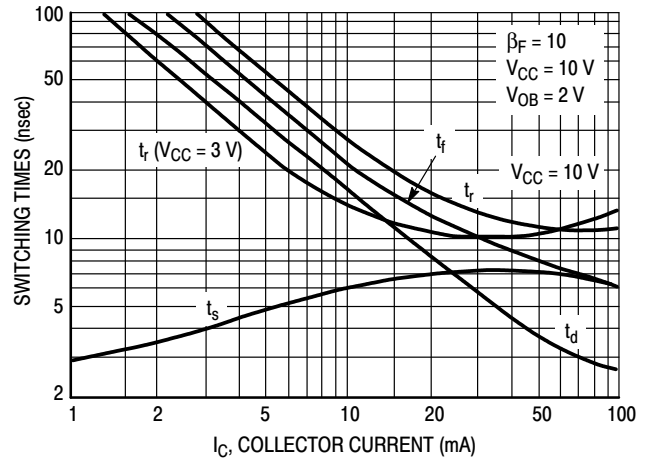


Figure 7. Typical Switching Times

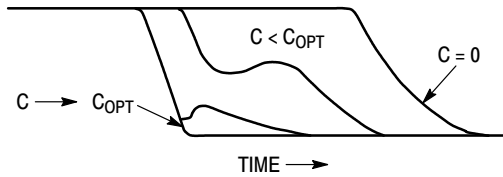


Figure 8. Turn-Off Waveform

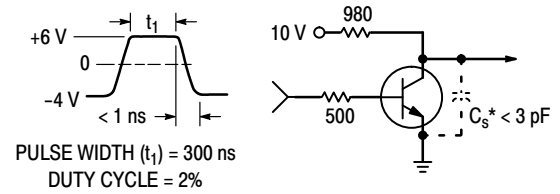


Figure 9. Storage Time Equivalent Test Circuit

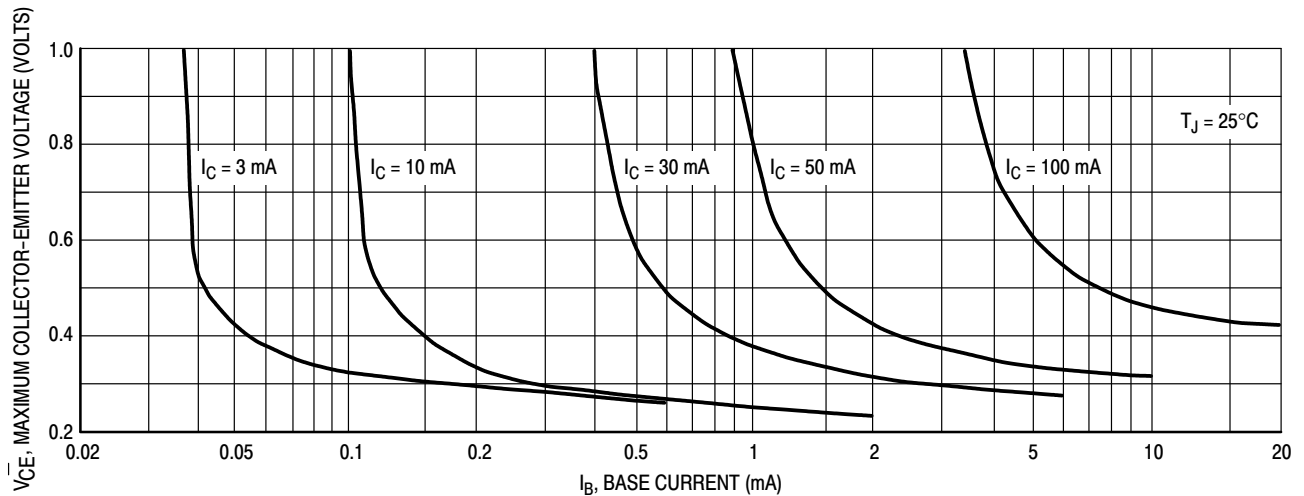


Figure 10. Maximum Collector Saturation Voltage Characteristics

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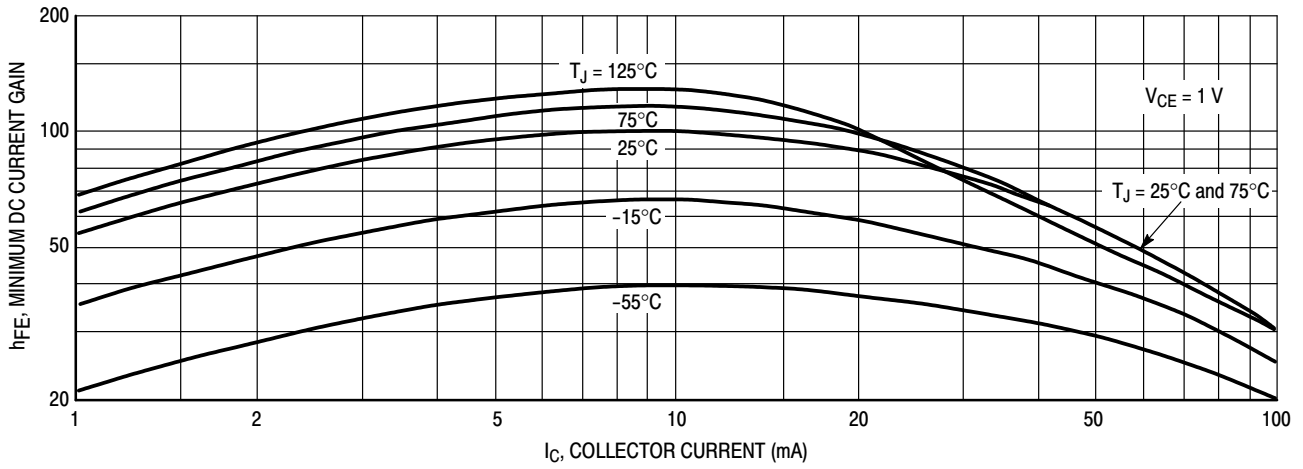


Figure 11. Minimum Current Gain Characteristics

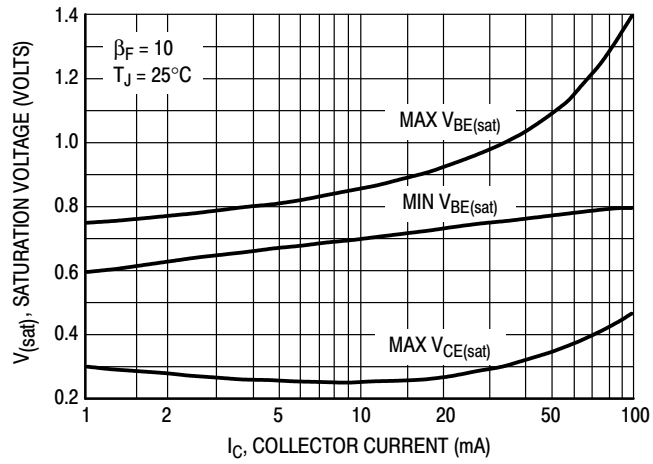
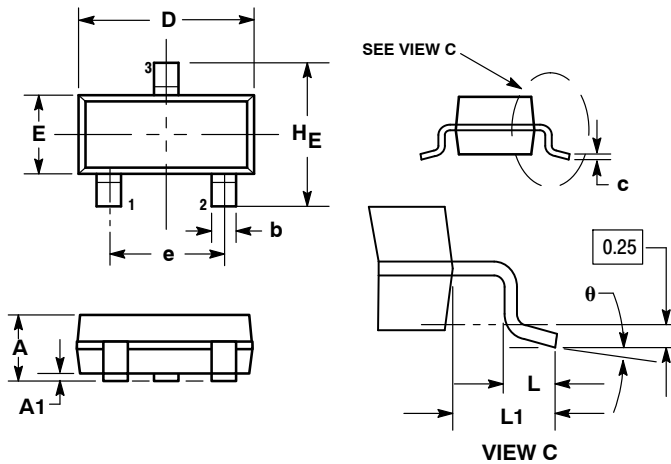


Figure 12. Saturation Voltage Limits

MMBT2369LT1G, MMBT2369ALT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AN



NOTES:

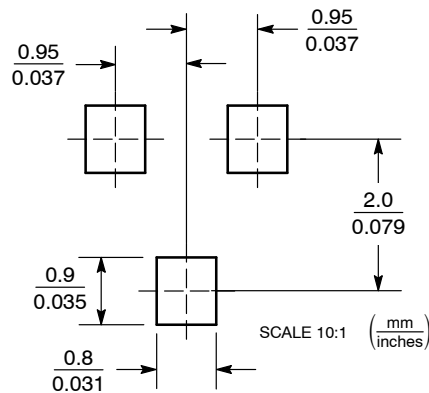
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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